

(2,54 mm) .100"

# SIGNAL POWER COMBO SYSTEM

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?HPFC](http://www.samtec.com?HPFC) or [www.samtec.com?HPMC](http://www.samtec.com?HPMC)

### Insulator Material:

Black Liquid Crystal Polymer

### Signal Contact (HPFC):

Phosphor Bronze

### Power Contact (HPFC):

BeCu

### Terminal (HPMC):

Phosphor Bronze

(Signal & Power)

### Plating:

Sn or Au over 50µ" (1,27 µm)

Ni on signal pins; Sn over 50µ" (1,27 µm) Ni on power pins

### Operating Temp Range:

-55°C to +105°C with Tin;

-55°C to +125°C with Gold

### Contact Resistance:

10 mΩ

### Insertion Depth:

(3,68 mm) .145" to

(8,26 mm) .325"

### Wiping Distance:

(0,381 mm) .015"

### Insertion Force:

(Single contact only)

5 oz (1,39 N) avg. (signal pins)

56 oz (15,57 N) avg. (power pins)

### Withdrawal Force:

(Single contact only)

3 oz (0,83 N) avg. (signal pins)

52 oz (14,46 N) avg. (power pins)

### Voltage Rating:

850 VAC/1201 VDC

### RoHS Compliant:

Yes

### Processing:

Lead-Free Solderable:

Yes

### SMT Lead Coplanarity:

(0,15 mm) .006" max (02-20)

(0,20 mm) .008" max (21-24)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



**Note:**  
Some lengths, styles and options are non-standard, non-returnable.

| HPFC             | 1          | SIGNAL PIN PER ROW | LEAD STYLE                                | SIGNAL PIN PLATING                                                                                            | D | POWER PINS | OPTION                                                                                                                                                               |
|------------------|------------|--------------------|-------------------------------------------|---------------------------------------------------------------------------------------------------------------|---|------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Mates with: HPMC | 02 thru 24 |                    | -01 = Through-Hole<br>-02 = Surface Mount | -L = 10µ" (0,25 µm)<br>Gold on contact area, Matte Tin on tail (Power Pins = All Matte Tin)<br>-T = Matte Tin |   | 02 thru 04 | -LC = Locking Clip (Manual placement required) (Not available with -01 lead style)<br>-K = (6,50 mm) .256" DIA Polyimide film Pick & Place Pad (5 positions minimum) |

Style -01 (Signal End)  
Style -01 (Power End)  
Style -02 (Signal End)  
Style -02 (Power End)

| HPMC             | 1          | SIGNAL PIN PER ROW | LEAD STYLE                    | SIGNAL PIN PLATING                                                                                            | D | POWER PINS |
|------------------|------------|--------------------|-------------------------------|---------------------------------------------------------------------------------------------------------------|---|------------|
| Mates with: HPFC | 02 thru 24 |                    | Specify LEAD STYLE from chart | -L = 10µ" (0,25 µm)<br>Gold on contact area, Matte Tin on tail (Power Pins = All Matte Tin)<br>-T = Matte Tin |   | 02 thru 04 |

| LEAD STYLE | A           |
|------------|-------------|
| -01, -02   | (5,84) .230 |
| -03, -04   | (8,13) .320 |